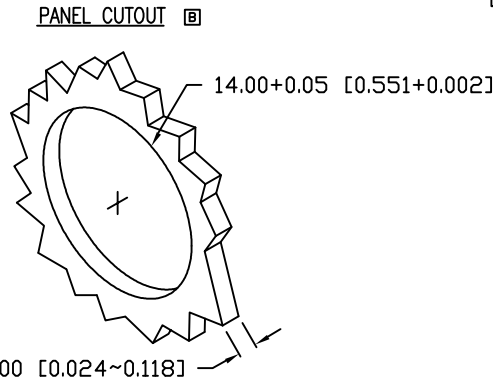
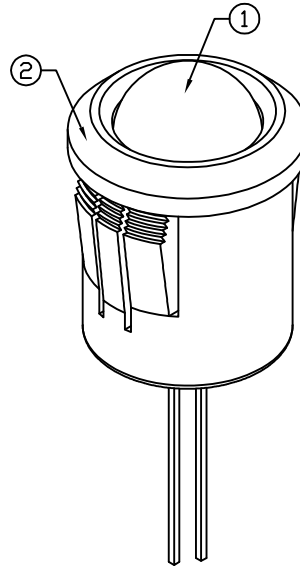
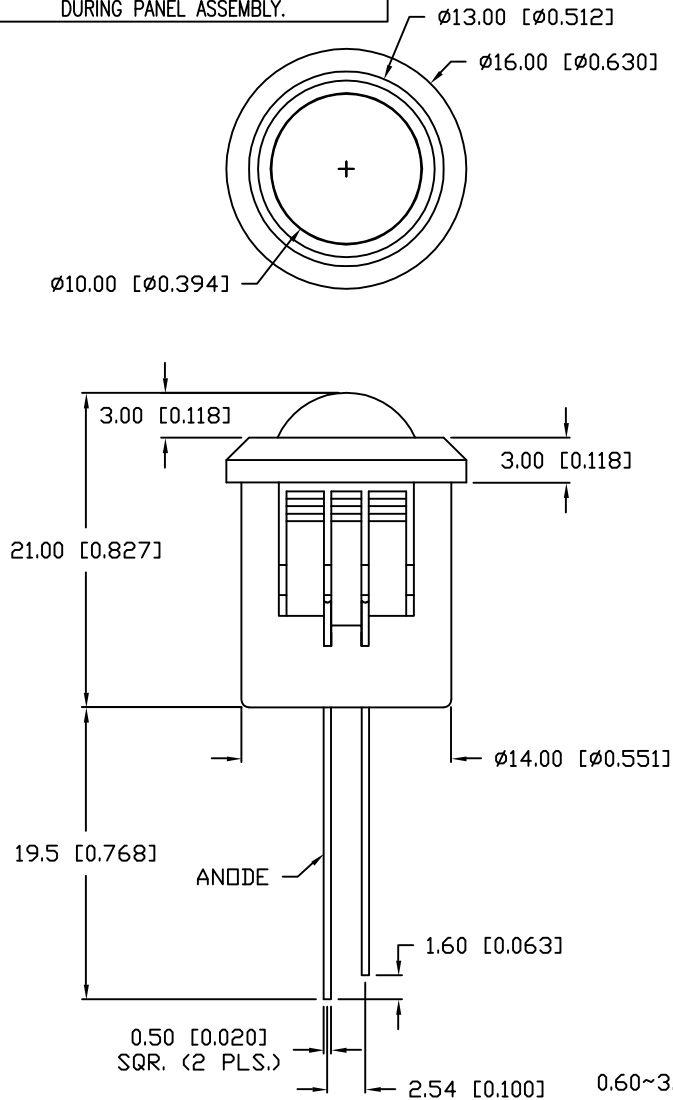


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CAUTION: PRESSURE SENSITIVE ASSEMBLY
 AVOID APPLYING PRESSURE TO LED
 DURING PANEL ASSEMBLY.



PART NUMBER
SSI-LXH1090SRD

REV.
D

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10112 & #10113.	4.18.96
B	E.C.N. #10539.	3.9.00
C	E.C.N. #10BRDR. & REDRAWN IN 3D.	1.5.02
D	E.C.N. #11626.	03.17.10

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660		nm	
FORWARD VOLTAGE		1.7	2.2	V_f	
REVERSE VOLTAGE	4.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		550		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	75	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

- SSL-LX100133SRD LED.
- SSH-RTF1090 HOLDER.
- UV EPOXY TO RETAIN LED IN HOLDER.

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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+DECIMAL PRECISION -0.00 MAX.=+0.00 -DECIMAL PRECISION

REV. D	PART NUMBER SSI-LXH1090SRD
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290 E. HELEN ROAD
 PALATINE, IL 60067-6976
 PHONE: +1.847.359.2790
 US WEB: www.lumex.com
 TW WEB: www.lumex.com.tw

T-10mm 660nm SUPER RED LED PANEL INDICATOR,
 RED DIFFUSED LENS.

RELIABILITY NOTE
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 7.14.93
			PAGE: 1 OF 1
			SCALE: N/A